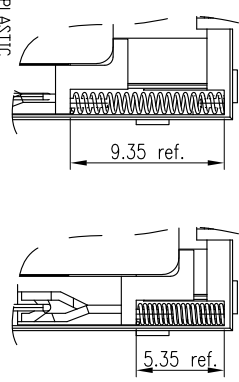
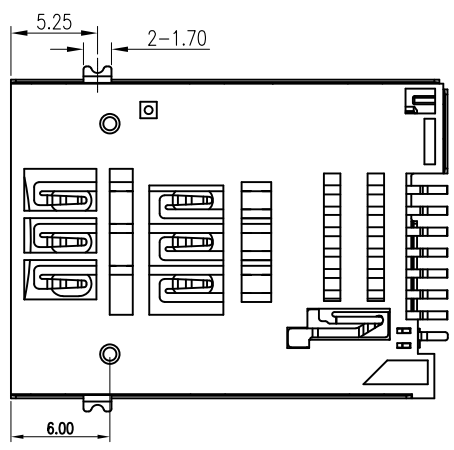
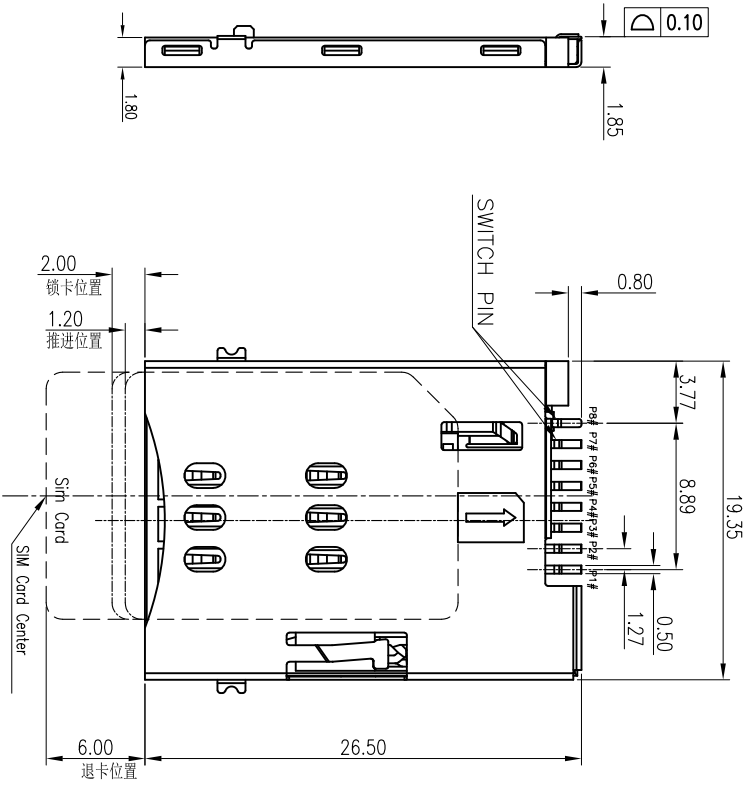
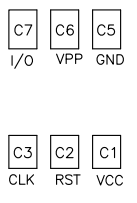
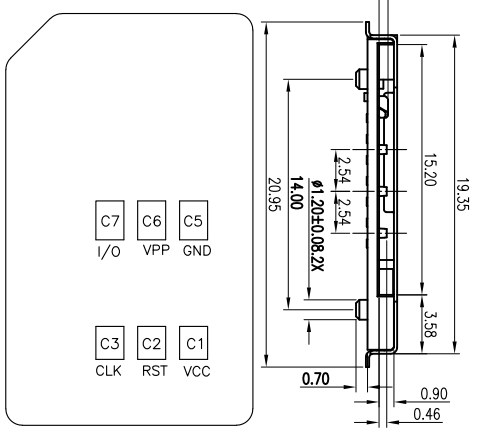


REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	2019.03.09			



NOTES:
 1. MATERIAL: DMATERIAL:
 2. HOUSING: HIGHT TEMPERATURE THERMOPLASTIC
 3. CONTACT: COPPER ALLOY
 4. SHELL: STEEL
 5. FINISH: 2(FINISH):
 6. CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
 7. MATE: - FIN PLATED ON SOLDER TAILS. WITH
 8. ENTIRE CONTACT UNDERPLATED NICKEL.
 9. SHELL: GOLD FLASH PLATED ON SOLDER TAILS
 10. 3(INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10°

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:1/O
P7#	POL
P8#	DET

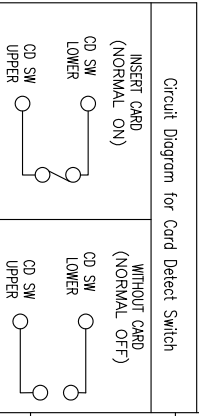


SIM 示意图
芯片面朝下视图

MILLIMETERS	INCH	UNITS	MM
X° ± 2'	X° ± 2'	MAT'L	SEE NOTES
.X ± 0.30	.XX ± 0.012	FINISH	SEE NOTES
.XX ± 0.20	.XXX ± 0.008	QTY	SEE NOTES
.XXX ± 0.10	.XXXX ± 0.004	DR:	Yang

PART NUMBER: MT102011312		TITLE: SIM card 6+2 pin push H1.8 (有定位柱)	
APPD: SeGdn		DWG NO: A-102011312	
CHKD: Yang		SCALE	SHEET
		1:1	1
		REV.	A

MINTRON TECHNOLOGY CO., LTD.



RECOMMENDED PCB LAYOUT(TOP VIEW)
 GENERAL TOLERANCES:±0.05
 SOLDER AREA
 NONE CIRCUIT DIAGRAM AREA